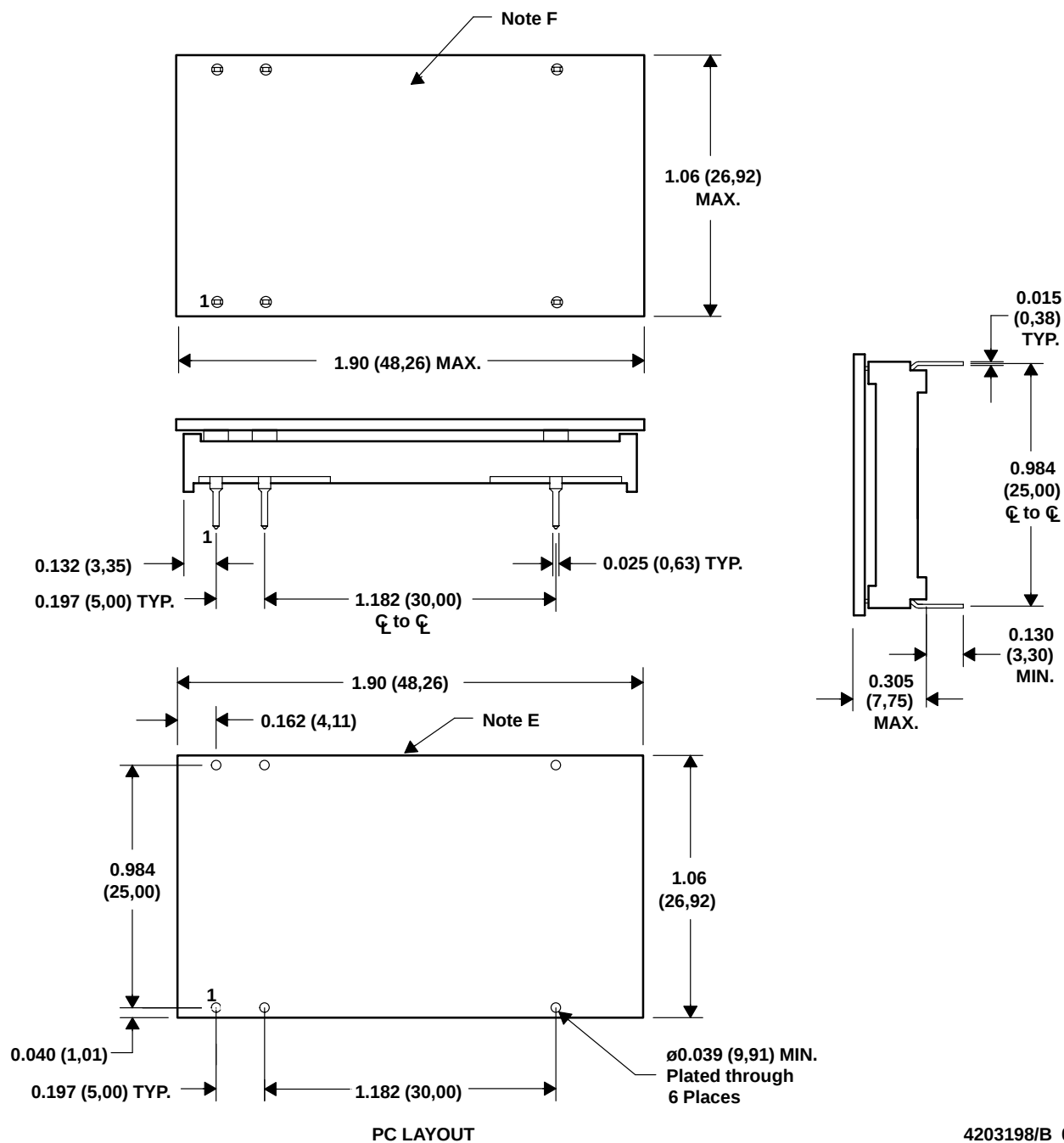


EGH (R-PDIP-T5)

PLASTIC DUAL-IN-LINE MODULE

Suffix A



4203198/B 08/01

- NOTES:
- A. All linear dimensions are in inches (mm).
 - B. This drawing is subject to change without notice.
 - C. 2 place decimals are ± 0.030 ($\pm 0,76$ mm).
 - D. 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 - E. Recommended mechanical keep-out area.
 - F. Keepout area, printed circuit board exposed.

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